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In re application of

Yutaka WADA et al.

Serial No. 09/916,305

Filed July 30, 2001

Attn: Application Branch

Attorney Docket No. 2001-1079

POLISHING METHOD USING AN
ABRADING PLATE

(Rule 1.53(b) Continuation-In-Part
of Serial No. 09/446,764 & 09/276,153,
Filed April 28, 1999 & March 25, 1999)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application, kindly amend the application as follows:

IN THE CLAIMS

Please add the following new claims:

42. A method for polishing an object comprising:
polishing the object by an abrading surface comprising abrasive particles and a binder for binding said abrasive particles, with supplying a first liquid not containing abrasive particles; and further polishing the object by a second polishing surface comprising polishing cloth.

43. A method according to claim 42, wherein said first liquid comprises water or active solution.

44. A method according to claim 42, wherein said first liquid comprises ionized water.

08/30/2001 BNGUYEN1 00000009 09916305

01 FC:103
02 FC:102

216.00 OP
160.00 OP